



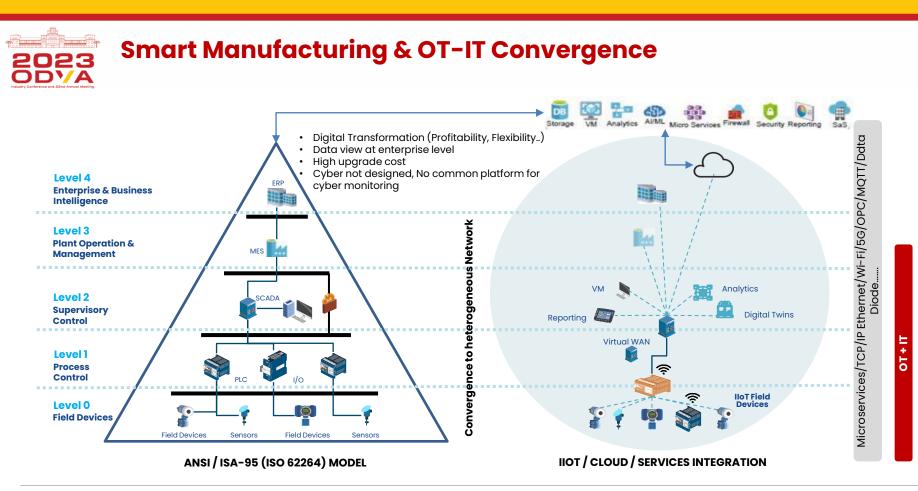
Leveraging 5G Networks & EtherNet/IP: Unleashing the Power of TSN, Clustered Networks, and Deterministic Connectivity for Sensor-to-Cloud Architecture

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Outline

- Smart Manufacturing & OT-IT Convergence ٠
- 5G in Smart Manufacturing
- 5G & Relevance of ISA-95 Purdue Model
- Typical Network Architecture for EtherNet/IP + Private 5G
- Integrating EtherNet/IP with 5G
 - OSI Layer Breakdown
 - Blended Architecture
- MVP for 5G Testing
- Reference Design
 - Hardware Architecture
 - Functional Architecture
- EtherNet/IP with Private 5G Use Cases & Applications
- Conclusion



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5G in Smart Manufacturing

The 5G specifications defined by 3GPP include the following elements that make it the next big thing for intelligent factories:

- 1. QoS (Quality of Service): 3GPP has defined four parameters for 5G based on the types of traffic,
 - Periodic Deterministic Traffic: Stringent requirements are defined.
 - Aperiodic Deterministic Traffic: No pre-set sending time, but stringent requirements in terms of timeliness and availability are defined.
 - Non-Deterministic Traffic: Specifying lesser stringent requirements.
 - Mixed Traffic: Minimum stringent requirements.
- 2. End-to-End Latency: As less as 0.5 milli second that goes up to 500 milli seconds
- 3. Data Rate: Up to Gbits/second
- 4. Communication Service Availability: 99.9% to 99.999999%
- 5. Seamless integration with wired technologies on the same machines



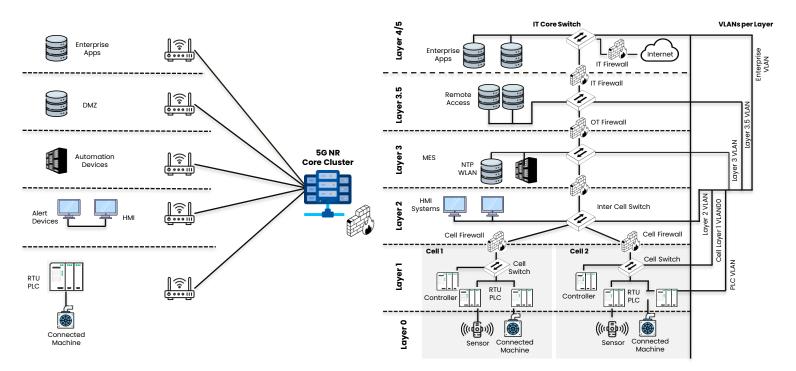
High-band or millimeter wave (mmWave) 5G

High speed but short range. High band 5G frequencies range from 24 GHz to 100 GHz, making it incredibly fast – enabling multi-gigabit per second speeds. But these high frequencies cause trouble going through buildings and walls, making it useful only for short distances.

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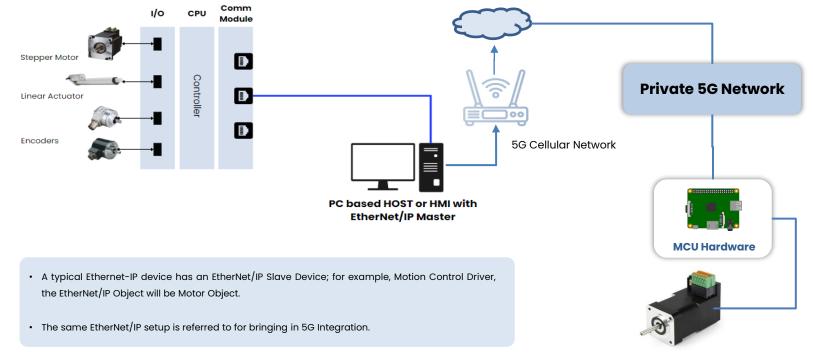


5G & Relevance of Purdue Model



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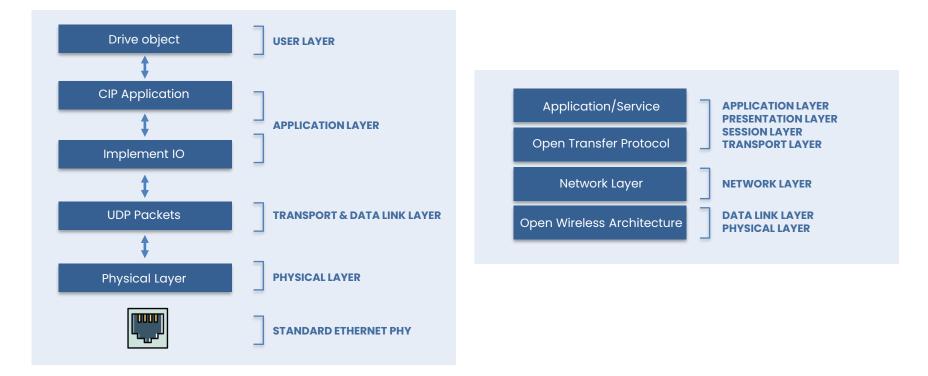




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OSI Layer Breakdown – Integrating EtherNet/IP with 5G



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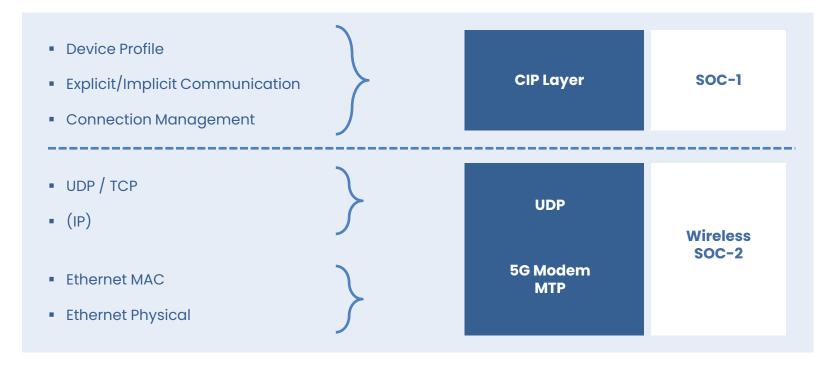
Blended Architecture – Integrating EtherNet/IP with 5G



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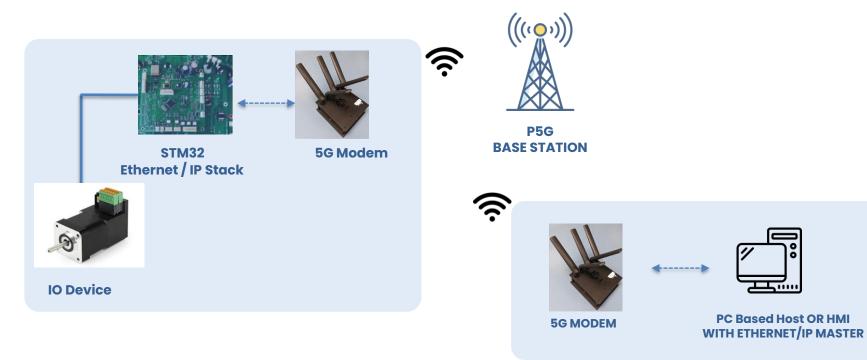


Blended Architecture – Integrating EtherNet/IP with 5G 2/3





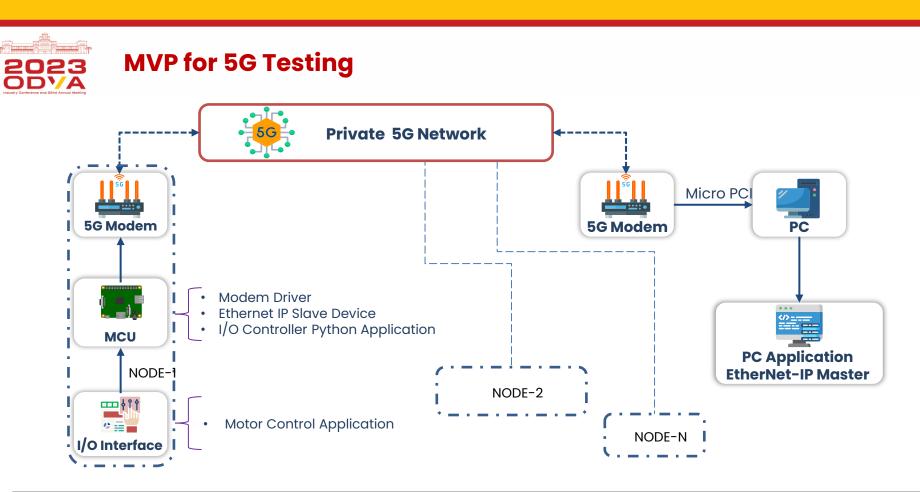
Blended Architecture – Integrating EtherNet/IP with 5G



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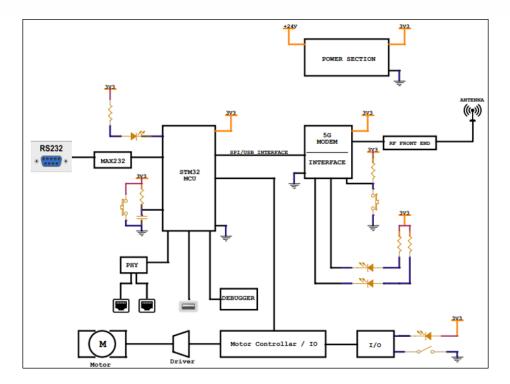
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Reference Design - Hardware Architecture



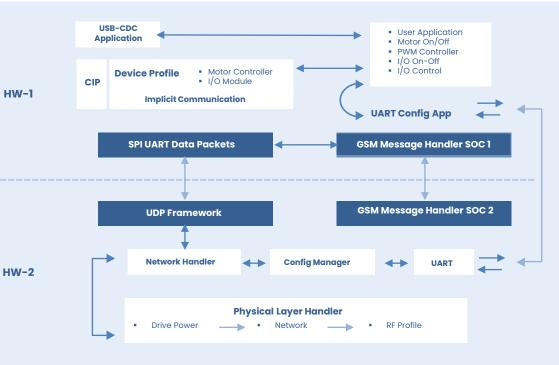
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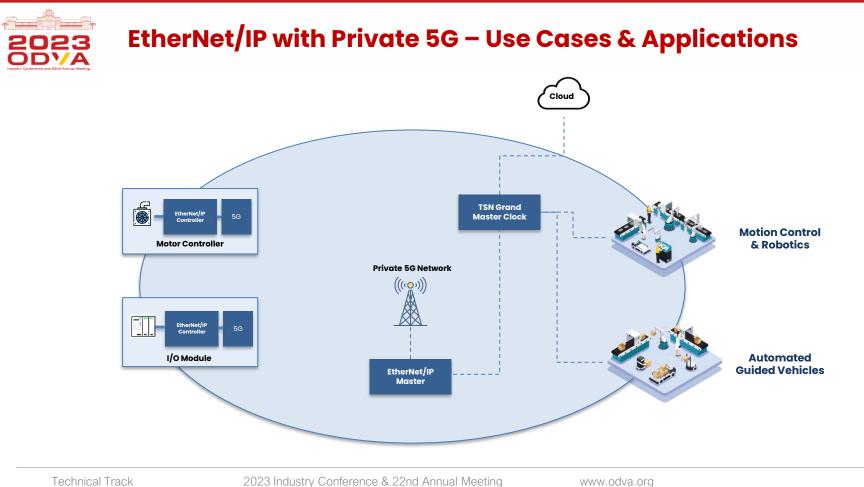
Reference Design – Functional Architecture

The above architecture describes the high-level software/firmware architecture of a 5G-based Ethernet/IP Device, which can control a DC motor's speed and handle some of the I/O functions.

- Encapsulation for EtherNet/IP to work with 5G.
- This architecture describes the message handling between the two SoCs.
- The two SoC hardware are interconnected over an SPI bus to have a maximum 10mbps connection.
- Inter-chip connection over serial (UART) interface with a USB-CDC connection device class was used to configure the SoCs.



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- The amalgamation of 5G networks with EtherNet/IP represents a pivotal advancement in industrial automation, further bolstered by the potential of Time-Sensitive Networking (TSN).
- This synergy promises ultra-responsive, deterministic, and broad bandwidth communication platforms uniquely suited to the multifaceted requirements of modern industrial ecosystems.
- Drawing upon collaborative insights from leaders like Rockwell Automation, Ericsson, Qualcomm, and Verizon, this integration crafts a foundational pathway for organizations aiming to exploit the full spectrum of real-time data communication.
- The outlined hardware and software architectures not only facilitate streamlined MVP developments but also position industries at the vanguard of a burgeoning digital evolution.



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